

AT28C010-12DM/883

Data Sheet

EEPROM 1M 5V SDP - 120NS MILTEM 883C

Manufacturers	Microchip Technology, Inc
Package/Case	CERDIP-32
Product Type	Memory
RoHS	
Lifecycle	



Images are for reference only

Please submit RFQ for AT28C010-12DM/883 or Email to us: sales@ovaga.com We will contact you in 12 hours.

<u>RFO</u>

General Description

The Microchip AT28C010 is a high-performance1-megabit Parallel EEPROM available in both Industrial and Military tempranges, offering access times to 120ns with power dissipation of 220mW (440mWmilitary). Deselected, CMOS standby current is less than 200µA (300µAmilitary). Access like static RAM for the read or write cycle without externalcomponents; a 128byte page register to allow writing of up to 128bytessimultaneously. Features an internal ErrorCorrection Circuit for extended endurance and improved data retention.Optional Software Data Protection mechanism guards against inadvertent writes; and an extra 128 bytes of EEPROMenables device identification or tracking.

The AT28C010 is also available DUAL MARKED where applicable with the appropriate Standard Military Drawing Number - 5962-382670xxMxx. See the separate MIL datasheet for exact availability.

Features

128 Kbits x 8 (1 megabit) $5V \pm 10\%$ Supply Parallel Interface 120ns access time Self-Timed Erase and Write Cycles (10 ms max) Page Write and Byte Write Data Polling for end of write detection Low Power Consumption Read / Write current 40 mA (Max) Standby current TTL 2 mA (Max), CMOS 200 µA (Max) Write-Protection Hardware Data Protection Software Data Protection High-endurance Option 100,000 erase/write cycles Data retention > 10 years **Temperature Ranges** Standard Temperature Range: -40°C to 85°C Military Temperature Range: -55°C to 125°C Available in Green (Pb/Halide-free) Packaging 32-lead, Plastic J-leaded Chip Carrier (PLCC) 32-lead, Plastic Thin Small Outline Package (TSOP) Available in dual marked (5962-382670xxx) CERAMIC Hermetic Packaging 32-Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline (Cerdip) 32-Lead, Non-Windowed, Ceramic Bottom-Brazed Flat Package (Flatpack) 32-Pad, Non-windowed, Ceramic, Leadless Chip Carrier (LCC)



Related Products



AT27C010-45JU Microchip Technology, Inc PLCC-32



AT24CM02-SSHD-B

Microchip Technology, Inc SOIC-8



24LC32AT-I/SN

Microchip Technology, Inc SOIC-8







AT24CM02-SSHM-B

Microchip Technology, Inc SOIC-8

AT24C512C-SSHM-T

Microchip Technology, Inc SOIC-8

AT24C04D-MAHM-T

Microchip Technology, Inc UDFN-8



AT28BV256-20SU

Microchip Technology, Inc SOIC-28



AT28C010E-12DM/883

Microchip Technology, Inc CERDIP-32